

Full Material Disclosure (材料成分表) :

Manufacturer Name (供应商公司名称) **Eaton Electronics Division**
 Part Number (产品料号) **S500-X-R**
 Product Name (产品名称) **Fuse**
 ES revision **F**

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 Title (职务): **Engineer**
 Date (日期): **5/30/2019**

Subcomponent 部件	Subcomponent PN 部件	Chemicals, compounds 物质成分名称	CAS # 化学索引号	Weight (g) 重量	Weight percentage 重量百分比	PPM 百万分含量	Remark 备注
Glass tube	FB010526	Glass	65997-17-3	0.2620	39.280%	392804	
Cap 5mm Ni plated	FC050623	Cu	7440-50-8	0.1740	26.092%	260924	
		Zn	7440-66-6	0.0937	14.050%	140497	
		Ni plating	7440-02-0	0.0033	0.488%	4876	
Element	FW030059	Ag	7440-22-4	0.0010	0.145%	1454	
Solder	FS441100	Sn	7440-31-5	0.1275	19.122%	191220	
		Cu	7440-50-8	0.0040	0.599%	5990	
		Sb	7440-36-0	0.0013	0.200%	1997	
		Ag	7440-22-4	0.0002	0.034%	339	

Total component weight 0.667 100%